

Semiconductor Bonding Market Size, Share, and Analysis, By Type (Die Bonder, Wafer Bonder, Flip Chip Bonder), By Process Type (Die To Die Bonding, Die To Wafer Bonding, Wafer To Wafer Bonding), By Application (RF Devices, Mems and Sensors, and Others), By Bonding Technology (Die Bonding Technology, Wafer Bonding Technology), and By Region (North America, Europe, Asia-Pacific, And Rest of the World) And Regional Forecast 2023-2032

<https://marketpublishers.com/r/S153848448C6EN.html>

Date: January 2024

Pages: 426

Price: US\$ 5,150.00 (Single User License)

ID: S153848448C6EN

Abstracts

Semiconductor Bonding Market Size, Share, and Analysis, By Type (Die Bonder, Wafer Bonder, Flip Chip Bonder), By Process Type (Die To Die Bonding, Die To Wafer Bonding, Wafer To Wafer Bonding), By Application (RF Devices, Mems and Sensors, and Others), By Bonding Technology (Die Bonding Technology, Wafer Bonding Technology), and By Region (North America, Europe, Asia-Pacific, And Rest of the World) And Regional Forecast 2023-2032

PRODUCT OVERVIEW

Semiconductor Bonding Market is expected to grow at a CAGR of 3.5% in the forecast period (2023-2032), with the market size valued at USD 0.82 billion in 2021 and projected to reach USD 1.2 billion by 2032.

Semiconductors are electrically conductive materials. Additionally, the semiconductor atom arrangement is a homogeneous structure, and the semiconductor bonding model is employed in the production of many fabrication equipment and many integrated

circuits. Further, semiconductors can be molecules like gallium arsenide or silicon. Rising demand for stacked die systems in IoT equipment, as well as the increasing popularity of hybrid and electric vehicles, have boosted semiconductor bonding's popularity in recent years. Moreover, semiconductors, also known as integrated circuits, help to improve the digital economy. Semiconductors, which are made up of a huge number of microscopic electronic components linked together, are known as the brains of modern electronic gadgets such as televisions, tablets, smartphones, and laptop computers.

MARKET HIGHLIGHTS

Semiconductor Bonding Market is expected to reach USD 1.2 billion, growing at a CAGR of 3.5% owing to the increasing use of stacked die technology in IoT devices, as well as the increasing demand for electric and hybrid automobiles in various locations. Additionally, rising demand for 3D semiconductor assembly and packaging, as well as increased usage of IoT and AI in the automotive sector, will open new opportunities for the semiconductor bonding industry.

Semiconductor Bonding Market Segments:

By Type

Die Bonder

Wafer Bonder

Flip Chip Bonder

By Process Type

Die to Die Bonding

Die to Wafer Bonding

Wafer to Wafer Bonding

By Application

RF Devices

Mems and Sensors

Others

By Bonding Technology

Die Bonding Technology

Wafer Bonding Technology

MARKET DYNAMICS

Growth Drivers

Increasing Use of Stacked Die Technology in IoT Devices t%li%Boost the Market

Integrated Circuit Industry is Growing

Restraint

High Ownership Costs is Hurting the Market

Key Players

Besi

ASM International

Kulicke & Soffa

Palomar Technologies

West-Bond, Inc.

SHINKAWA Electric Co., Ltd.

F&K Delvotec Bondtechnik GmbH

Micr%li%Assembly Technologies, Ltd.

S?SS MicroTec SE

Finetech GmbH & Co. KG

EV Group (EVG)

SET Corporation

MRSI Systems

TORAY Engineering Co., Ltd.

DIAS Automation

Other Prominent Players (Company Overview, Business Strategy, Key Product Offerings, Financial Performance, Key Performance Indicators, Risk Analysis, Recent Development, Regional Presence, SWOT Analysis)

Global Laboratory Temperature Control Units Market is further segmented by region into:

North America Market Size, Share, Trends, Opportunities, Y-o-Y Growth, CAG.R – United States and Canada

Latin America Market Size, Share, Trends, Opportunities, Y-o-Y Growth, CAGR – Mexico, Argentina, Brazil and Rest of Latin America

Europe Market Size, Share, Trends, Opportunities, Y-o-Y Growth, CAGR – United Kingdom, France, Germany, Italy, Spain, Belgium, Hungary, Luxembourg, Netherlands, Poland, NORDIC, Russia, Turkey and Rest of Europe

Asia Pacific Market Size, Share, Trends, Opportunities, Y-o-Y Growth, CAGR – India, China, South Korea, Japan, Malaysia, Indonesia, New Zealand, Australia and Rest of APAC

Middle East and Africa Market Size, Share, Trends, Opportunities, Y-o-Y Growth, CAGR – North Africa, Israel, GCC, South Africa and Rest of MENA

Reasons to Purchase this Report

Qualitative and quantitative analysis of the market based on segmentation involving both economic as well as non-economic factors

Provision of market value (USD Billion) data for each segment and sub-segment

Indicates the region and segment that is expected to witness the fastest growth as well as to dominate the market

Analysis by geography highlighting the consumption of the product/service in the region as well as indicating the factors that are affecting the market within each region

Competitive landscape which incorporates the market ranking of the major players, along with new service/product launches, partnerships, business expansions, and acquisitions in the past five years of companies profiled

Extensive company profiles comprising of company overview, company insights, product benchmarking, and SWOT analysis for the major market players

The current as well as the future market outlook of the industry with respect to recent developments which involve growth opportunities and drivers as well as challenges and restraints of both emerging as well as developed regions

Includes in-depth analysis of the market of various perspectives through Porter's five forces analysis

Provides insight into the market through Value Chain

Market dynamics scenario, along with growth opportunities of the market in the years to come

3-month post-sales analyst support.

Contents

1.EXECUTIVE SUMMARY

- 1.1. Regional Market Share
- 1.2.Business Trends
- 1.3. Semiconductor Bonding Market: COVID-19 Outbreak
- 1.4. Regional Trends
- 1.5. Segmentation Snapshot

2. RESEARCH METHODOLOGY

- 2.1.Research Objective
- 2.2. Research Approach
- 2.3. Data Sourcing and Methodology
- 2.4.Primary Research
- 2.5.Secondary Research
 - 2.5.1.Paid Sources
 - 2.5.2. Public Sources
- 2.6. Market Size Estimation and Data Triangulation

3. MARKET CHARACTERISTICS

- 3.1.Market Definition
- 3.2.Semiconductor Bonding Market: COVID-19 Impact
- 3.3. Key Segmentations
- 3.4.Key Developments
- 3.5.Allied Industry Data

4.SEMICONDUCTOR BONDING MARKET – INDUSTRY INSIGHTS

- 4.1. Industry Segmentation
- 4.2.COVID-19 overview on world economy
- 4.3.Industry ecosystem Channel analysis
- 4.4.Innovation & Sustainability

5. MACROECONOMIC INDICATORS

6. RECENT DEVELOPMENTS

Semiconductor Bonding Market Size, Share, and Analysis, By Type (Die Bonder, Wafer Bonder, Flip Chip Bonder),...

7. MARKET DYNAMICS

- 7.1.Introduction
- 7.2. Growth Drivers
- 7.3. Market Opportunities
- 7.4.Market Restraints
- 7.5. Market Trends

8.RISK ANALYSIS

9. MARKET ANALYSIS

- 9.1.Porters Five Forces
- 9.2. PEST Analysis
 - 9.2.1.Political
 - 9.2.2. Economic
 - 9.2.3. Social
 - 9.2.4. Technological

10.SEMICONDUCTOR BONDING MARKET

- 10.1.Overview
- 10.2. Historical Analysis (2019-2021)
 - 10.2.1. Market Size, Y-o-Y Growth (%) and Market Forecast

11. SEMICONDUCTOR BONDING MARKET SIZE & FORECAST 2022A-2032F

- 11.1. Overview
- 11.2.Key Findings
- 11.3.Market Segmentation
 - 11.3.1.By Type
 - 11.3.1.1.Die Bonder
 - 11.3.1.1.1.By Value (USD Million) 2022-2032F
 - 11.3.1.1.2. Market Share (%) 2022-2032F
 - 11.3.1.1.3. Y-o-Y Growth (%) 2022-2032F
 - 11.3.1.2.Wafer Bonder
 - 11.3.1.2.1. By Value (USD Million) 2022-2032F
 - 11.3.1.2.2.Market Share (%) 2022-2032F

- 11.3.1.2.3.Y-o-Y Growth (%) 2022-2032F
- 11.3.1.3.Flip Chip Bonder
 - 11.3.1.3.1. By Value (USD Million) 2022-2032F
 - 11.3.1.3.2.Market Share (%) 2022-2032F
 - 11.3.1.3.3.Y-o-Y Growth (%) 2022-2032F
- 11.3.2. By Process Type
 - 11.3.2.1.Die-to-Die Bonding
 - 11.3.2.1.1. By Value (USD Million) 2022-2032F
 - 11.3.2.1.2.Market Share (%) 2022-2032F
 - 11.3.2.1.3.Y-o-Y Growth (%) 2022-2032F
 - 11.3.2.2. Die-to-Wafer Bonding
 - 11.3.2.2.1.By Value (USD Million) 2022-2032F
 - 11.3.2.2.2. Market Share (%) 2022-2032F
 - 11.3.2.2.3. Y-o-Y Growth (%) 2022-2032F
 - 11.3.2.3. Wafer-to-Wafer Bonding
 - 11.3.2.3.1.By Value (USD Million) 2022-2032F
 - 11.3.2.3.2. Market Share (%) 2022-2032F
 - 11.3.2.3.3. Y-o-Y Growth (%) 2022-2032F
- 11.3.3.By Bonding Technology
 - 11.3.3.1 Die Bonding Technology
 - 11.3.3.1.1By Value (USD Million) 2022-2032F
 - 11.3.3.1.2 Market Share (%) 2022-2032F
 - 11.3.3.1.3 Y-o-Y Growth (%) 2022-2032F
 - 11.3.3.2Wafer Bonding Technology
 - 11.3.3.2.1 By Value (USD Million) 2022-2032F
 - 11.3.3.2.2Market Share (%) 2022-2032F
 - 11.3.3.3.1 Y-o-Y Growth (%) 2022-2032F
- 11.3.4 By Application
 - 11.3.4.1 RF Devices
 - 11.3.4.1.1By Value (USD Million) 2022-2032F
 - 11.3.4.1.2 Market Share (%) 2022-2032F
 - 11.3.4.1.3 Y-o-Y Growth (%) 2022-2032F
 - 11.3.4.2Mems and Sensors
 - 11.3.4.2.1 By Value (USD Million) 2022-2032F
 - 11.3.4.2.2Market Share (%) 2022-2032F
 - 11.3.4.2.3Y-o-Y Growth (%) 2022-2032F
 - 11.3.4.3Others
 - 11.3.4.3.1 By Value (USD Million) 2022-2032F
 - 11.3.4.3.2Market Share (%) 2022-2032F

11.3.4.3.3Y-o-Y Growth (%) 2022-2032F

12.NORTH AMERICA SEMICONDUCTOR BONDING MARKET SIZE & FORECAST 2022A-2032F

12.1.Overview

12.2. Key Findings

12.3. Market Segmentation

12.3.1.By Type

12.3.2. By Process Type

12.3.3. By Application

12.3.4. By Bonding Technology

12.4. Country

12.4.1. United States

12.4.2. Canada

13.EUROPE SEMICONDUCTOR BONDING MARKET SIZE & FORECAST 2022A-2032F

13.1.Overview

13.2. Key Findings

13.3. Market Segmentation

13.3.1.By Type

13.3.2. By Process Type

13.3.3. By Application

13.3.4. By Bonding Technology

13.4.Country

13.4.1.Germany

13.4.2. United Kingdom

13.4.3. France

13.4.4. Italy

13.4.5. Spain

13.4.6. Russia

13.4.7. Rest of Europe (BENELUX, NORDIC, Hungary, Turkey & Poland)

14.ASIA-PACIFIC SEMICONDUCTOR BONDING MARKET SIZE & FORECAST 2022A-2032F

14.1. Overview

- 14.2. Key Findings
- 14.3. Market Segmentation
 - 14.3.1. By Type
 - 14.3.2. By Process Type
 - 14.3.3. By Application
 - 14.3.4. By Bonding Technology
- 14.4. Country
 - 14.4.1. India
 - 14.4.2. China
 - 14.4.3. South Korea
 - 14.4.4. Japan
 - 14.4.5. Rest of APAC

15. MIDDLE EAST AND AFRICA SEMICONDUCTOR BONDING MARKET SIZE & FORECAST 2022A-2032F

- 15.1. Overview
- 15.2. Key Findings
- 15.3. Market Segmentation
 - 15.3.1. By Type
 - 15.3.2. By Process Type
 - 15.3.3. By Application
 - 15.3.4. By Bonding Technology
- 15.4. Country
 - 15.4.1. Israel
 - 15.4.2. GCC
 - 15.4.3. North Africa
 - 15.4.4. South Africa
 - 15.4.5. Rest of Middle East and Africa

16. LATIN AMERICA SEMICONDUCTOR BONDING MARKET SIZE & FORECAST 2022A-2032F

- 16.1. Overview
- 16.2. Key Findings
- 16.3. Market Segmentation
 - 16.3.1. By Type
 - 16.3.2. By Process Type
 - 16.3.3. By Application

- 16.3.4. By Bonding Technology
- 16.4. Country
 - 16.4.1. Mexico
 - 16.4.2. Brazil
 - 16.4.3. Rest of Latin America

17. COMPETITIVE LANDSCAPE

- 17.1. Company market share, 2021
- 17.2. Key player overview
- 17.3. Key stakeholders

18. COMPANY PROFILES

- 18.1. Besi
 - 18.1.1. Company Overview
 - 18.1.2. Financial Overview
 - 18.1.3. Key Product; Analysis
 - 18.1.4. Company Assessment
 - 18.1.4.1. Product Portfolio
 - 18.1.4.2. Key Clients
 - 18.1.4.3. Market Share
 - 18.1.4.4. Recent News & Development (Last 3 Yrs.)
 - 18.1.4.5. Executive Team
- 18.2. ASM International
- 18.3. Kulicke & Soffa
- 18.4. Palomar Technologies
- 18.5. SHINKAWA Electric Co., Ltd.
- 18.6. West-Bond, Inc.
- 18.7. F&K Delvotec Bondtechnik GmbH
- 18.8. Micro Assembly Technologies, Ltd.
- 18.9. S?SS MicroTec SE
- 18.10. Finetech GmbH & Co. KG
- 18.11. EV Group (EVG)
- 18.12. SET Corporation
- 18.13. MRSI Systems
- 18.14. TORAY Engineering Co., Ltd.
- 18.15. DIAS Automation
- 18.16. Other Prominent Players

19. APPENDIX

20. CONSULTANT RECOMMENDATION

I would like to order

Product name: Semiconductor Bonding Market Size, Share, and Analysis, By Type (Die Bonder, Wafer Bonder, Flip Chip Bonder), By Process Type (Die To Die Bonding, Die To Wafer Bonding, Wafer To Wafer Bonding), By Application (RF Devices, Mems and Sensors, and Others), By Bonding Technology (Die Bonding Technology, Wafer Bonding Technology), and By Region (North America, Europe, Asia-Pacific, And Rest of the World) And Regional Forecast 2023-2032

Product link: <https://marketpublishers.com/r/S153848448C6EN.html>

Price: US\$ 5,150.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/S153848448C6EN.html>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:
Last name:
Email:
Company:
Address:
City:
Zip code:
Country:
Tel:
Fax:
Your message:

****All fields are required**

Customer signature _____

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms

& Conditions at <https://marketpublishers.com/docs/terms.html>

To place an order via fax simply print this form, fill in the information below
and fax the completed form to +44 20 7900 3970